

# Material Composition Data



Product: OV7604C7

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## OV7604C7 - SM Oscillator Low Power

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Electrode	Chromium	Cr	7440-47-3	0.000	0.00
	Gold	Au	7440-57-5	0.005	100.00
Gold Bumps	Gold	Au	7440-57-5	0.025	100.00
Housing	Ceramic	Al <sub>2</sub> O <sub>3</sub>	1344-28-1	6.300	100.00
IC	Gold	Au	7440-57-5	0.020	5.88
	Silicon	Si	7440-21-3	0.320	94.12
Lid	Ceramic	Al <sub>2</sub> O <sub>3</sub>	1344-28-1	4.580	99.85
	Gold plate	Au	7440-57-5	0.002	0.04
	Nickel plate	Al <sub>2</sub> O <sub>3</sub>	1344-28-1	0.005	0.11
Resonator	Quartz	SiO <sub>2</sub>	14808-60-7	0.270	100.00
Termination	Gold	Au	7440-57-5	0.017	5.14
	Molybdenum	Mo	7439-98-7	0.264	79.76
	Nickel	Ni	7440-02-0	0.050	15.11
conductive adhesive	Silicones/siloxanes	Silicones/siloxanes	68037-58-1	0.011	12.22
	Silver	Ag	7440-22-4	0.079	87.78
solder preform	Gold	Au	7440-57-5	0.304	80.00
	Tin	Sn	7440-31-5	0.076	20.00
<b>Total Mass:</b>				<b>12.328 mg</b>	

John Hems  
 Quality Manager  
 Email: j.hems@golledge.com